TOSHIBA Intelligent Power Device Silicon Monolithic Power MOS Integrated Circuit

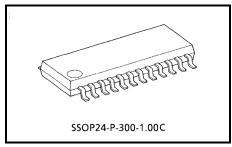
TPD2007F

Low-Side Power Switch Array (8 Channels) for Motors, Solenoids, and Lamp Drivers

The TPD2007F is an 8-channel low-side switch array. The IC has a vertical MOSFET output which can be directly driven from a CMOS or TTL logic circuit (e.g., an MPU). It offers overcurrent and overtemperature protection functions.

Features

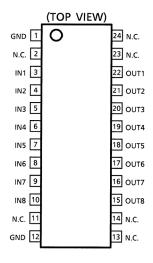
- 8-channel low-side switch array incorporating an N-channel power MOSFET (1.4Ω max)
- Can directly drive a power load from a microprocessor.
- Built-in protection against overtemperature and overcurrent
- · 8-channel access enables space-saving design.
- High operating voltage: 40 V
- Low on-resistance: $1.4 \Omega \max @V_{IN} = 5 \text{ V}$, $I_D = 0.5 \text{ A}$ (per channel)
- · Supports parallel operation.
- · Built-in active clamp circuit
- Supplied in an SSOP-24 package (300 mil) in embossed taping.

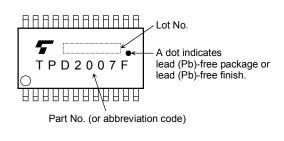


Weight: 0.29 g (typ.)

Pin Assignment

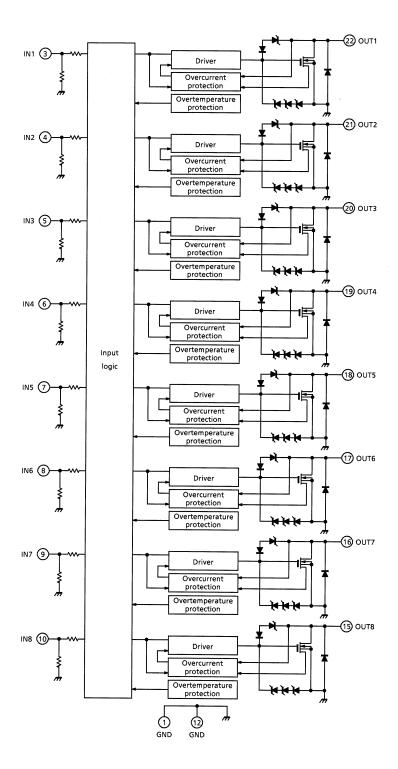
Marking





Note: This product has a MOS structure and is sensitive to electrostatic discharge. When handling this product, ensure that the environment is protected against electrostatic discharge.

Block Diagram

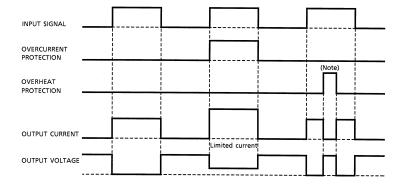


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Pin Description

Pin No.	Symbol	Description
1	GND	GND pin; in common with the pin no.12 internally.
2	N.C.	-
3	IN1	Control input pin for channel 1 and built-in pull-down resistor (300 kΩ typ.)
4	IN2	Control input pin for channel 2 and built-in pull-down resistor (300 kΩ typ.)
5	IN3	Control input pin for channel 3 and built-in pull-down resistor (300 kΩ typ.)
6	IN4	Control input pin for channel 4 and built-in pull-down resistor (300 kΩ typ.)
7	IN5	Control input pin for channel 5 and built-in pull-down resistor (300 kΩ typ.)
8	IN6	Control input pin for channel 6 and built-in pull-down resistor (300 kΩ typ.)
9	IN7	Control input pin for channel 7 and built-in pull-down resistor (300 kΩ typ.)
10	IN8	Control input pin for channel 8 and built-in pull-down resistor (300 kΩ typ.)
11	N.C.	_
12	GND	GND pin; in common with the pin no.1 internally.
13	N.C.	_
14	N.C.	_
15	OUT8	Output pin for channel 8
16	OUT7	Output pin for channel 7
17	OUT6	Output pin for channel 6
18	OUT5	Output pin for channel 5
19	OUT4	Output pin for channel 4
20	OUT3	Output pin for channel 3
21	OUT2	Output pin for channel 2
22	OUT1	Output pin for channel 1
23	N.C.	_
24	N.C.	_

Timing Chart



Note: The overheating detector circuits feature hysteresis. After overheating is detected, normal operation is restored only when the junction temperature falls by the hysteresis amount (10°C typ.) in relation to the overheating detection temperature.

Truth Table

Input Signal	Output Signal	State	
L	Н	Normal	
Н	L	Nomia	
L	Н	Overcurrent protection	
Н	Internally limited	Overcurrent protection	
L	Н	Overtemperature protection	
Н	Н	Overtemperature protection	

Absolute Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	40	V	
Input voltage	V _{IN}	- 0.5 ~ 7	V	
Output current	I _D	Internally Limited	Α	
Power dissipation	D	0.8	\\\	
(operating all channels, ta = 25°C)	P _T	-0.5 ~ 7 V Internally Limited A	VV	
Single pulse avalanche energy	E _{AS}	10	mJ	
Operating temperature	T _{opr}	− 40 ~ 85	°C	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	−55 ~ 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

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Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristic	Symbol	Rating	Unit	
Thermal resistance junction to	7 D	156.3	°C / W	
ambient (operating all channels, ta = 25°c)	ΣR _{th (j-a)}	104.2 (Note)	C/W	

Note: 60 mm × 60 mm × 1.6 mm when mounted on a glass epoxy PCB (DC)

Electrical Characteristics (Unless otherwise specified, T_i = 25°C)

Characteristic		Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Drain-source clamp voltage		V _{(BR) DSS}	_	I _D = 10 mA, V _{IN} = 0 V	40	_	_	V
Input voltage		V _{th}	_	V _{DS} = 24 V, I _{DS} = 1 mA	0.8	_	2.0	V
Input current		I _{IL}	_	V _{IN} = 0 V	-10	_	10	μА
		I _{IH}	_	V _{IN} = 5 V	_	140	300	
On resistance		R _{DS(ON)}	_	V _{IN} = 5 V, I _{O =} 0.5 A	_	1.0	1.4	Ω
Off current		I _{DSS}	_	V _{DS} = 40V	_	_	100	μA
Overcurrent protection		I _{S(1)}	_	V_{DS} = 12 V, V_{IN} = 5 V, R_L = 3 Ω	1	2	3	A
		I _{S(2)}	_	$V_{DS} = 30 \text{ V}, V_{IN} = 5 \text{ V},$ $R_L = 3\Omega$	0.7	_	2	
Overtemperature	Temperature	TSD	_	V _{IN} = 5 V	_	160	_	°C
Protection	Hysteresis	ΔTSD	_	_	_	10	_	
Switching time		t _{ON}	1	V _{DD} = 12 V, R _L = 24Ω, V _{IN} = 0 V / 5 V	_	10	50	- µs
		t _{OFF}	1		_	10	50	
Operating input voltage protection circuit		V _{IN(P)}	_	_	3.9	_	6.0	٧
Drain-source diode forward voltage		V _{DSF}	_	IF = 1 A, V _{IN} = 0 V	_	_	1.6	V

Description of Protector Circuit

(1) Overtemperature Protection

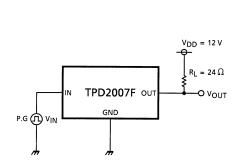
• The overheating detector circuits feature hysteresis. After overheating is detected, normal operation is restored only when the junction temperature falls by the hysteresis amount (10°C typ.) in relation to the overheating detection temperature.

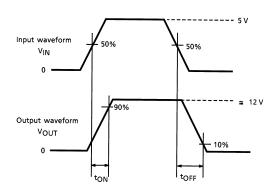
(2) Overcurrent Protection

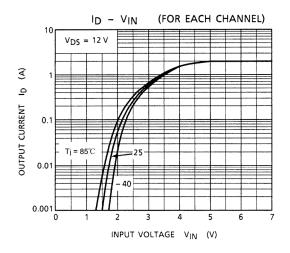
• When overcurrent is detected, the overcurrent limiter function limits the output current. Normal operation is restored when the load current drops below the overcurrent detection value.

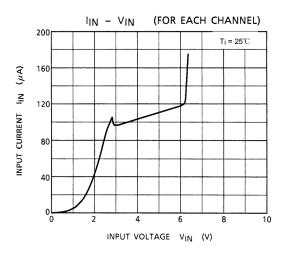
Test Circuit

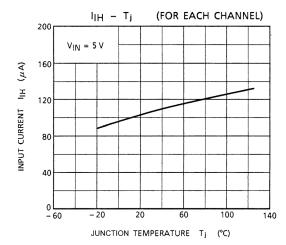
Switching Time

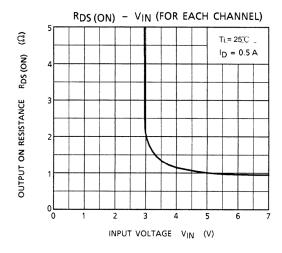


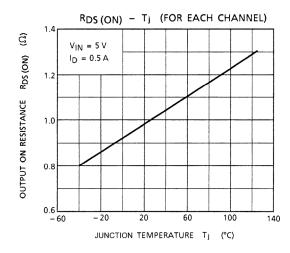


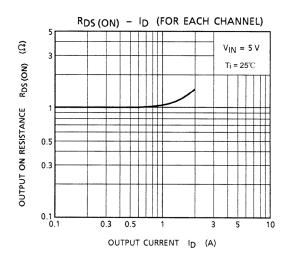


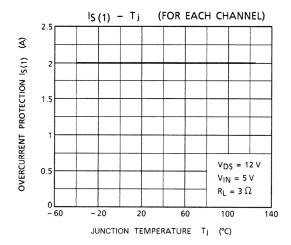


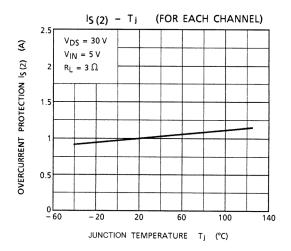


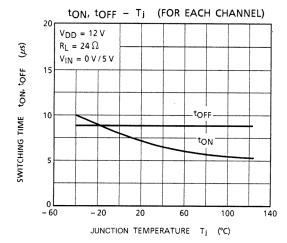


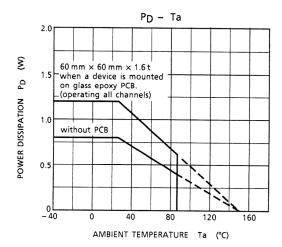


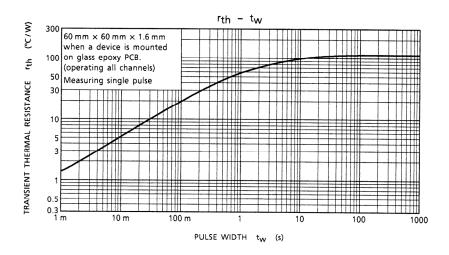












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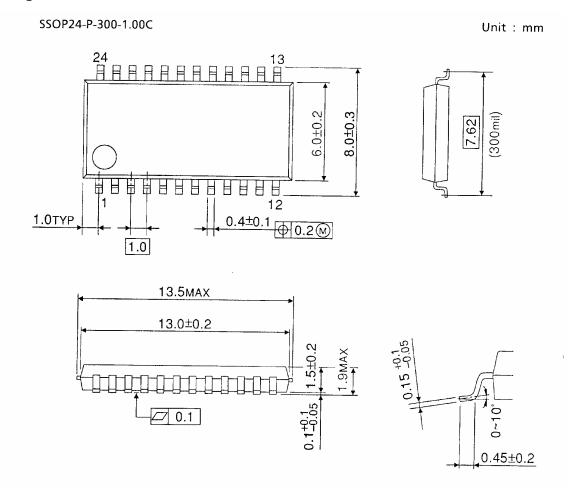
Moisture-Proof Packing

After the pack is opened, the devices should be used within 48 hours and in a 30°C, 60% RH environment. Embossed-tape packing cannot be baked. Devices so packed must be within their allowable time limits after unpacking, as specified on the packing.

Standard tape packing quantity: 2000 devices / reel (EL1)

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Package Dimensions



Weight: 0.29 g (typ.)

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